

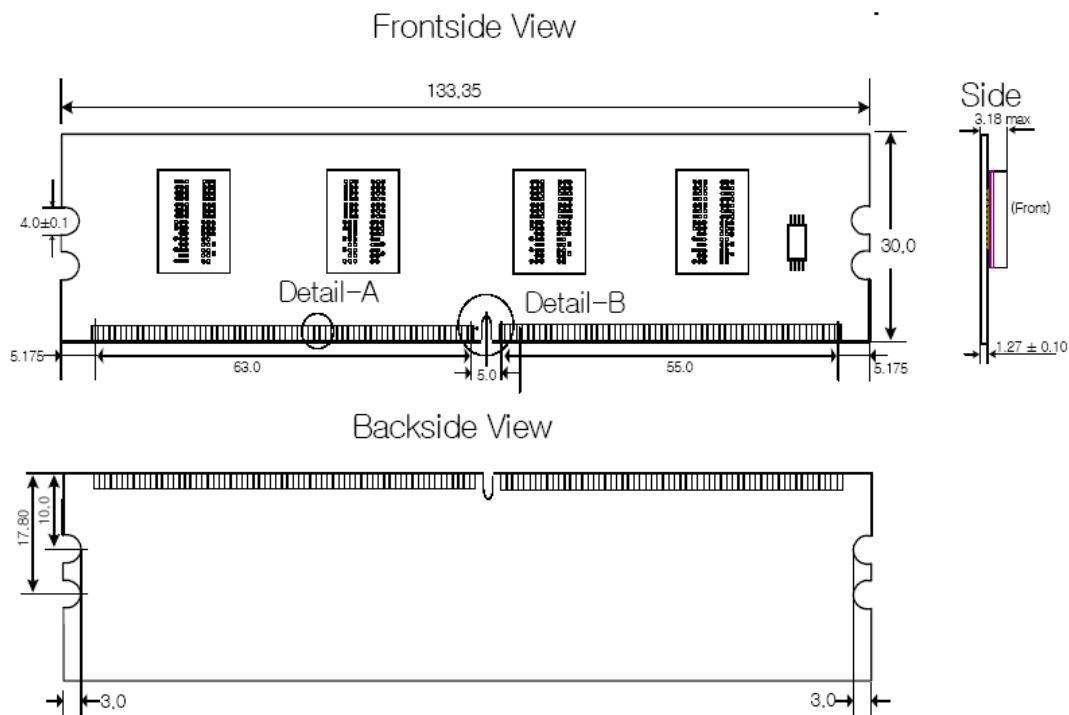
Memory Module Data Sheet H326424E

256MB 32M x 64-bit DDR2 533 (PC2-4200)

SPECIFICATIONS;

- 256MB (32M x 64-bit) Unbuffered DDR2 533Mhz DIMM
- 84-ball FBGA 32M x 16 (8M x 16 bit x 4 Bank/200Mhz) x Four DRAM
- 240-pin Dual in-line memory module with Gold Plated Contacts
- Dimm Dimensions 133.35 x 30 x 3.18 (mm)
- Programmable CAS Latency Supported - CL 4
- Row Cycle Time (tRC) – 56.25ns
- Auto Refresh Cycle Time (tRFC)- 105ns
- Row Active Time (tRAS) - 45ns
- Clock Cycle Time (tCK) – 3750ps (max)
- Power Supply Voltage – 1.8V (+/- .01V)
- Operating Temperature (TA) - 0~55 Celsius

PACKAGE DIMENSIONS



NOTE: The module described in this data sheet is one of several configurations available under this part number. All configurations are compatible but the DRAM combination and the module height may vary from what is described. However, in no configurations will the module height exceed 31.75mm.